



952-D6 FLUX-PEN®

Low-Solids No-Clean Flux-Pen® for Lead-bearing and Lead-free Alloys

Product Description

Kester 952-D6 Flux-Pen® is a no-clean, non-corrosive, halide-free Flux-Pen® that is specifically designed for lead-free rework of conventional and surface mount circuit board assemblies. Essentially no residue remains after soldering. 952-D6 Flux-Pen® was developed with a modified surface tension to aid in soldering boards that have surface mount and high component densities. This comprehensive formulation possesses improved wetting characteristics and also exhibits superior corrosion inhibiting properties and provides a non-tacky residue. A major advantage of this flux is the reduced odor associated with the soldering process. 952-D6 Flux-Pen® incorporates a small amount of rosin for higher reliability.

Performance Characteristics:

- Residues almost colorless
- Improves soldering performance
- Reduced odor associated with soldering process
- Eliminates the need and expense of cleaning
- Non-corrosive tack-free residues
- Contains < 0.5% Rosin
- Compliant to GR-78-CORE
- Classified as ORL0 per J-STD-004

RoHS Compliance

This product meets the requirements of the Restriction of Hazardous Substances (RoHS) Directive, 2011/65/EU for the stated banned substances.

Physical Properties

Specific Gravity: 0.812 ± 0.005
Anton Paar DMA @ 25°C

Percent Solids (theoretical): 3.1%
Tested to J-STD-004, IPC-TM-650, Method 2.3.34

Acid Number (typical): 21.4 mg KOH/g of flux
Tested to J-STD-004, IPC-TM-650, Method 2.3.13

Reliability Properties

Copper Mirror Corrosion: Low
Tested to J-STD-004, IPC-TM-650, Method 2.3.32

Chloride and Bromides: None Detected
Tested to J-STD-004, IPC-TM-650, Method 2.3.35

SIR, IPC (typical): Pass
Tested to J-STD-004, IPC-TM-650, Method 2.6.3.3

Corrosion Test: Low
Tested to J-STD-004, IPC-TM-650, Method 2.6.15

Fluorides by Spot Test: Pass
Tested to J-STD-004, IPC-TM-650, Method 2.3.35.1

	Blank	952-D6
Day 1	2.7 × 10 ¹⁰ Ω	9.4 × 10 ¹⁰ Ω
Day 4	1.3 × 10 ¹⁰ Ω	7.8 × 10 ¹⁰ Ω
Day 7	9.8 × 10 ¹⁰ Ω	6.3 × 10 ¹⁰ Ω

Silver Chromate: Pass
Tested to J-STD-004, IPC-TM-650, Method 2.3.33

Flux Application

952-D6 Flux-Pen[®] is applied to circuit boards via Flux-Pen[®] for rework of printed wire assemblies.

Process Considerations

952-D6 Flux-Pen[®] should only be applied to areas that will be fully heated by the soldering iron or other reflow tool. Care should be taken to avoid flooding the assembly. The surface tension has been adjusted to help the flux form a thin film on the board surface allowing rapid solvent evaporation.

Cleaning

952-D6 Flux-Pen[®] flux residues are non-conductive, non-corrosive and do not require removal in most applications.

Storage, Handling and Shelf Life

952-D6 Flux-Pen[®] is flammable. Store away from sources of ignition. Shelf life is 2 years from date of manufacture when handled properly and held at 10-25°C (50-77°F). The cap must be in place when not being used.

Health and Safety

This product, during handling or use, may be hazardous to your health or the environment. Read the Safety Data Sheet and warning label before using this product.